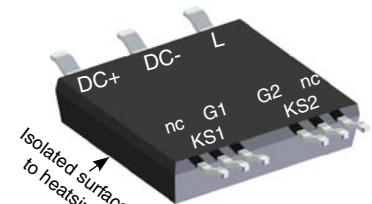
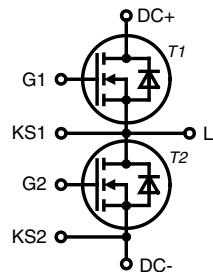


CoolMOS™ 1) Power MOSFET

ISOPLUS™ - electrically isolated surface to heatsink
Surface Mount Power Device

I_{D25} = 50 A
V_{DSS} = 600 V
R_{DS(on) max} = 45 mΩ



E72873

MOSFETs T1, T2

Symbol	Conditions	Maximum Ratings		
V _{DSS}	T _{VJ} = 25°C to 150°C	600	V	
V _{GS}		±20	V	
I _{D25}	T _C = 25°C	50	A	
I _{D80}	T _C = 80°C	38	A	
E _{AS}	single pulse	1950	mJ	
E _{AR}	repetitive	3	mJ	
dV/dt	MOSFET dV/dt ruggedness V _{DS} = 0...480 V	50	V/ns	

Symbol **Conditions****Characteristic Values**(T_{VJ} = 25°C, unless otherwise specified)

		min.	typ.	max.	
R _{DSon}	I _D = 44 A; V _{GS} = 10 V		40	45	mΩ
V _{GS(th)}	I _D = 3 mA; V _{DS} = V _{GS}	2.5	3	3.5	V
I _{DSS}	V _{DS} = V _{DSS} ; V _{GS} = 0 V; T _{VJ} = 25°C T _{VJ} = 125°C		50	10	μA
I _{GSS}	V _{DS} = 0 V; V _{GS} = ± 20 V			100	nA
C _{iss} C _{oss}	V _{GS} = 0 V; V _{DS} = 100 V; f = 1 MHz	6800 320			pF
Q _g Q _{gs} Q _{gd}	V _{DS} = 400 V; I _D = 44 A V _{GS} = 10 V; R _G = 3.3 Ω	150 35 50	190		nC
t _{d(on)} t _r t _{d(off)} t _f E _{on} E _{off}	Resistive switching T _{VJ} = 125°C V _{DS} = 380 V; I _D = 30 A V _{GS} = 10 V; R _G = 3.3 Ω	22 10 120 12 70 22			ns ns ns ns μJ μJ
t _{d(on)} t _r t _{d(off)} t _f E _{on} E _{off} E _{rec(off)}	Inductive switching T _{VJ} = 25°C V _{DS} = 380 V; I _D = 30 A V _{GS} = 10 V; R _G = 330 Ω	900 400 520 18 5.2 0.18			ns ns ns mJ mJ mJ
R _{thJC} R _{thJH}	with heatsink compound; IXYS test setup		0.6	0.4	K/W K/W

Features

- **Fast CoolMOS™ 1)**
power MOSFET 4th generation
 - high blocking capability
 - lowest resistance
 - avalanche rated for unclamped inductive switching (UIS)
 - low thermal resistance due to reduced chip thickness

Package

- isolated surface to heatsink
- low coupling capacity between pins and heatsink
- PCB space saving
- enlarged creepage towards heatsink
- application friendly pinout
- low inductive current path
- high reliability

Applications

- Switch mode power supplies (SMPS)
- Soft switching topologies
- Resonant converter

¹⁾ CoolMOS™ is a trademark of Infineon Technologies AG.

Source-Drain Diodes of T1/T2

Symbol	Conditions	Maximum Ratings		
I_{S25}	$T_C = 25^\circ C$	50	A	
I_{S80}	$T_C = 80^\circ C$	38	A	
Symbol	Conditions	Characteristic Values		
	$(T_{VJ} = 25^\circ C, \text{ unless otherwise specified})$			
		min.	typ.	max.
V_{SD}	$I_F = 44 A; V_{GS} = 0 V$		0.95	1.25
t_{rr} Q_{RM} I_{RM}	$I_F = 44 A; -di_F/dt = 100 A/\mu s; V_R = 400 V$		600 17 60	ns μC A

Component

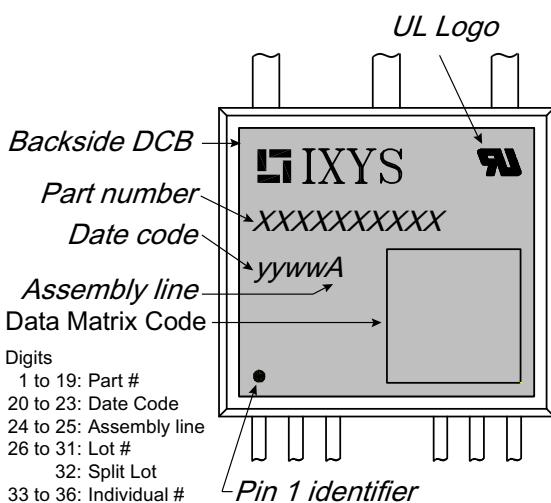
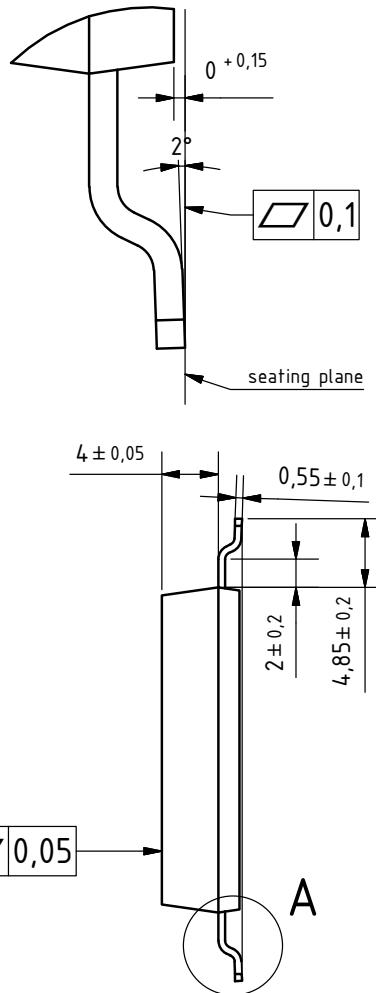
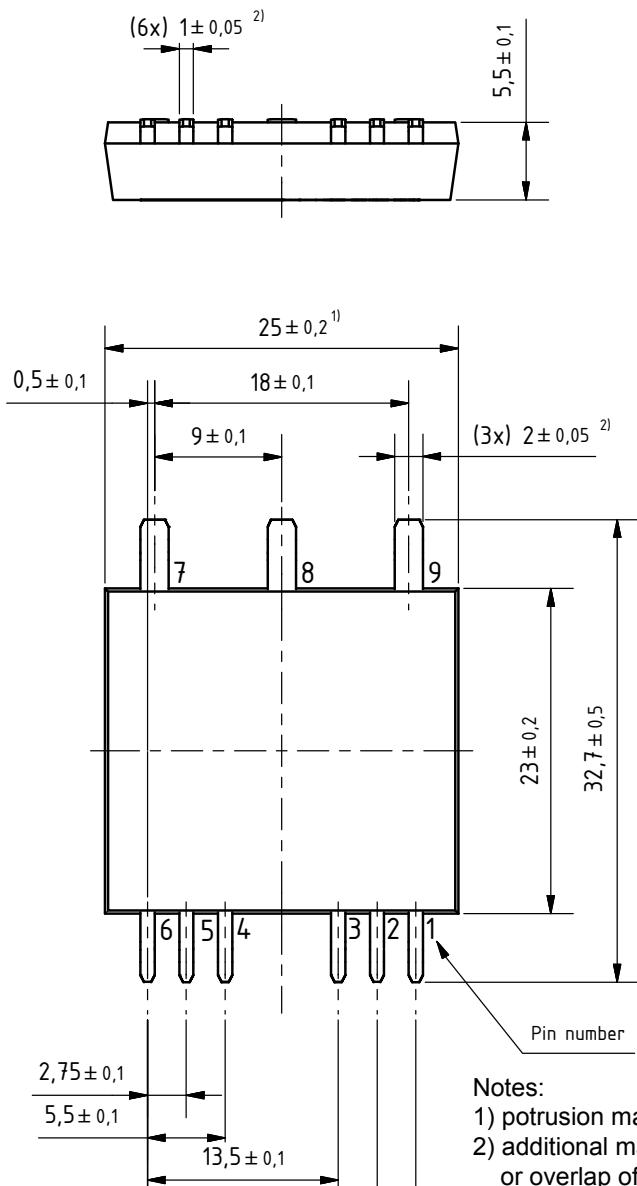
Symbol	Conditions	Maximum Ratings		
T_{VJ}		-55...+150	$^\circ C$	
T_{stg}		-55...+125	$^\circ C$	
V_{ISOL}	$I_{ISOL} \leq 1 mA; 50/60 Hz$	2500	V~	
F_c	mounting force	40 ... 130	N	

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
C_p	coupling capacity between shorted pins and backside metal		90	pF
d_s, d_a	pin - pin	1.65		mm
d_s, d_a	pin - backside metal	4		mm
CTI		400		
Weight			8	g

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	MKE38P600LB-TRR	MKE38P600LB	Tape&Reel	200	510486
	MKE38P600LB	MKE38P600LB	Blister	45	480601

Dimensions in mm
(1 mm = 0.0394")

A (8 : 1)



20130506b

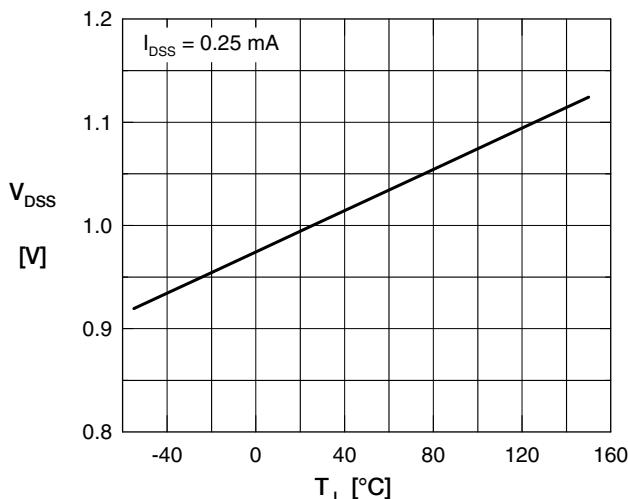


Fig.1 Drain source breakdown voltage
versus temperature T_{VJ}

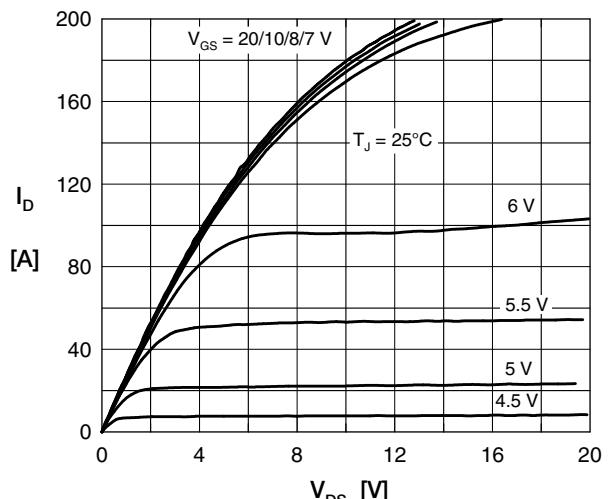


Fig. 2 Typ. output characteristics

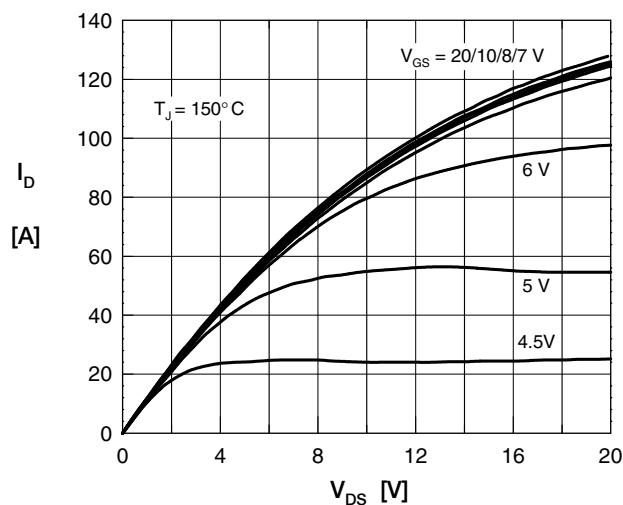


Fig. 3 Typ. output characteristics

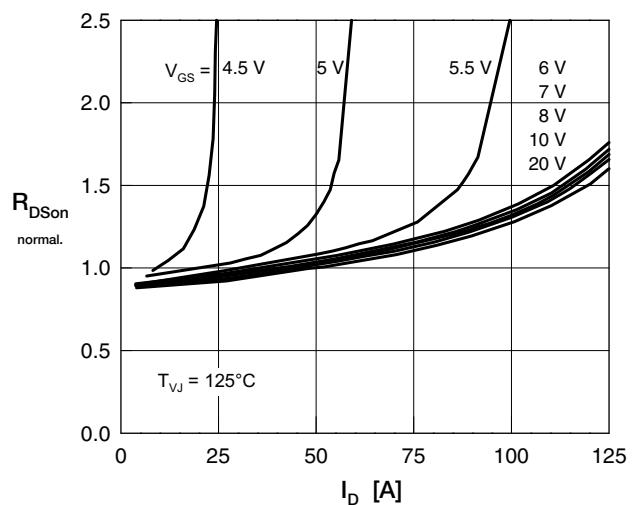


Fig. 4 Drain source on-state resistance
 $R_{DS(\text{on})}$ versus I_D

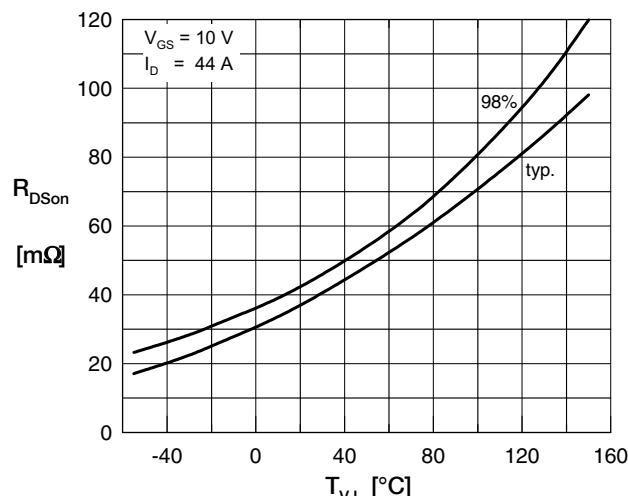


Fig. 5 Drain source on-state resistance
 $R_{DS(\text{on})}$ vs. junction temperature T_{VJ}

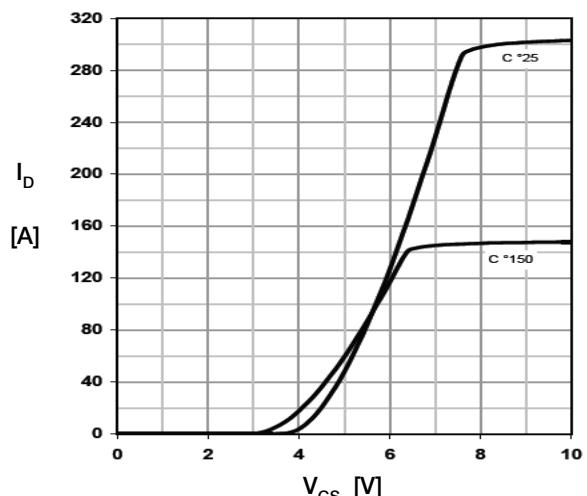


Fig. 6 Typ. transfer characteristics

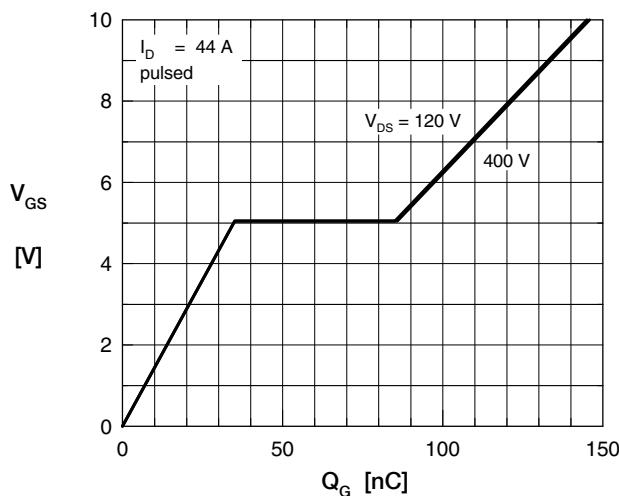


Fig. 7 Typ. turn-on gate charge

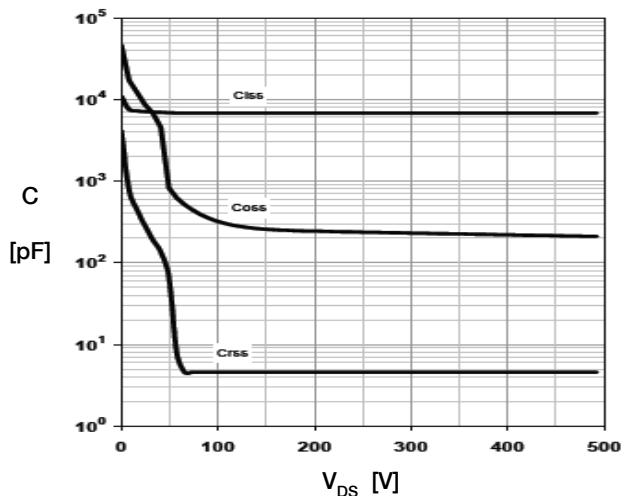


Fig. 8 Typ. capacities, MOSFET only

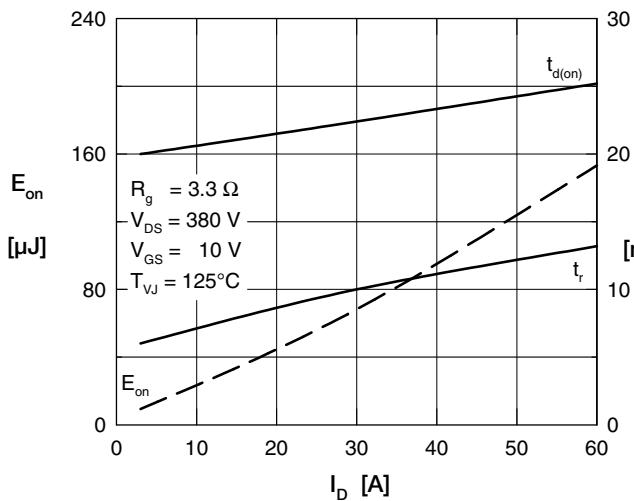


Fig. 9 Typ. turn-on energy and switching times versus collector current, resistive switching

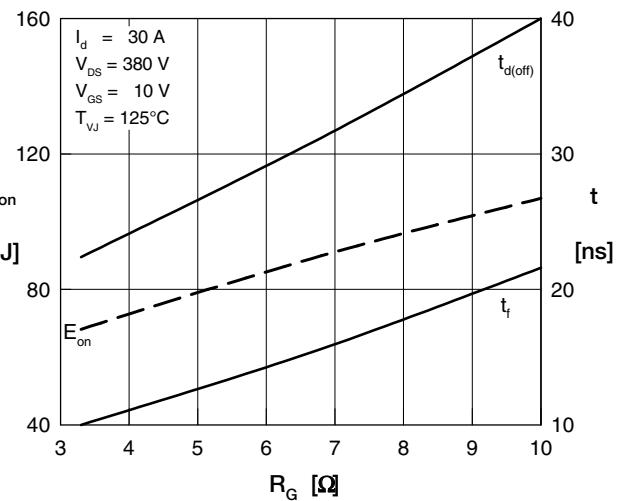


Fig. 10 Typ. turn-on energy and switching times versus gate resistor, resistive switching

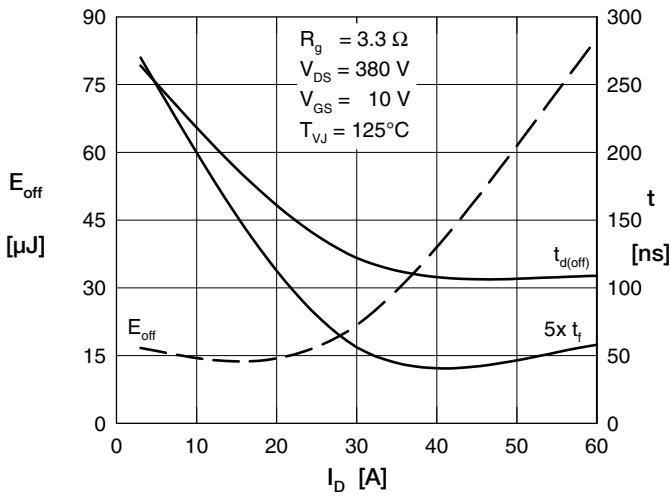


Fig. 11 Typ. turn-off energy and switching times vs. collector current, resistive switching

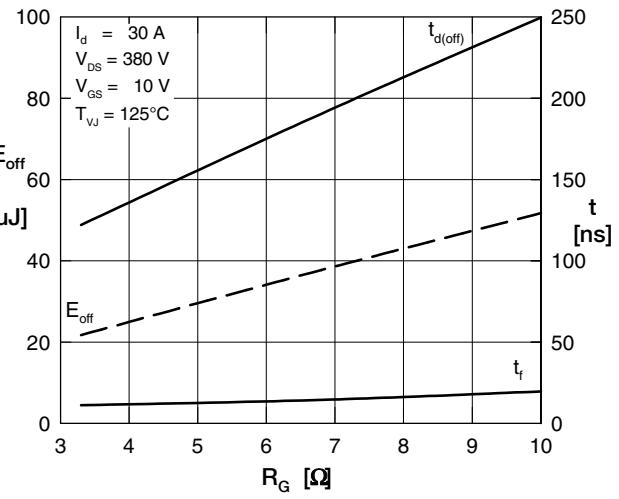


Fig. 12 Typ. turn-off energy and switching times versus gate resistor, resistive switching

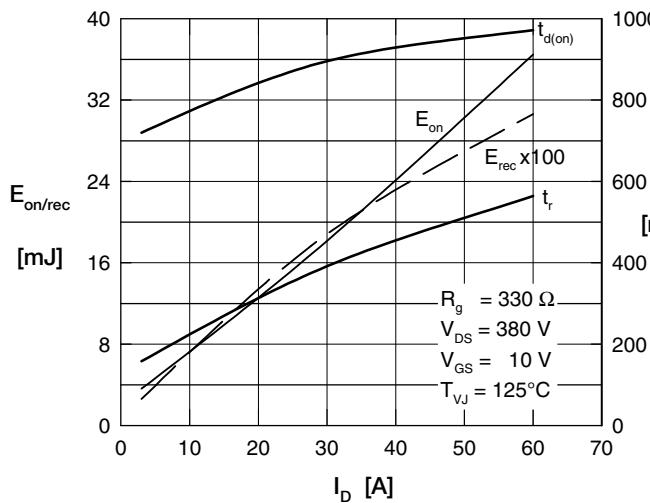


Fig. 13 Typ. turn-on energy & switching times versus collector current, inductive switching (phaseleg)

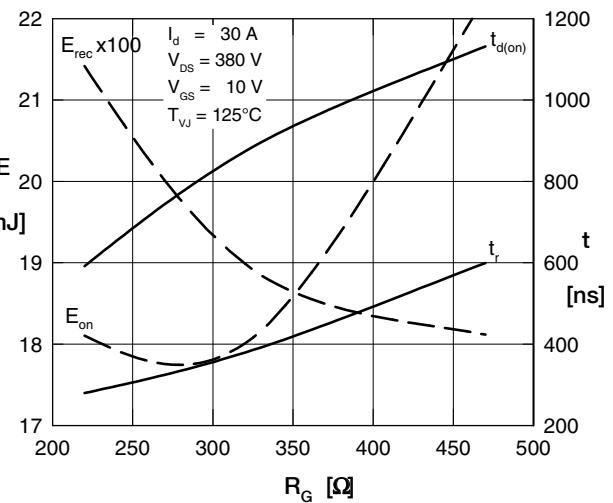


Fig. 14 Typ. turn-on energy & switching times versus gate resistor, inductive switching (phaseleg)

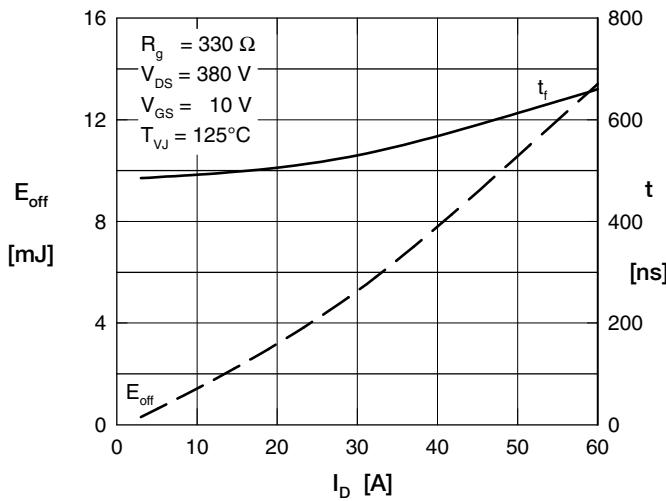


Fig. 15 Typ. turn-off energy & switching times versus collector-current, inductive switching (phaseleg)

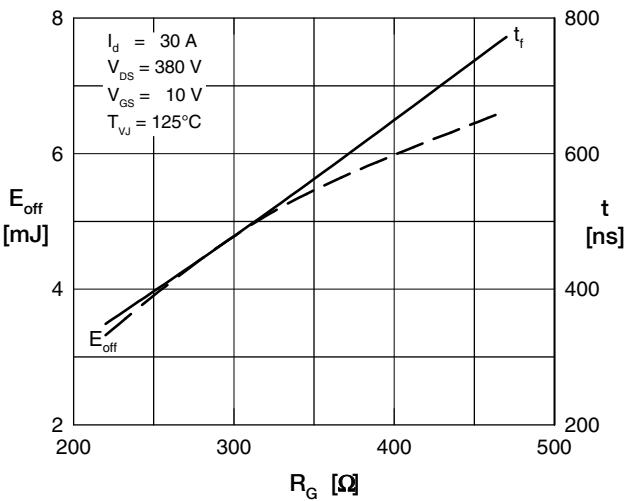


Fig. 16 Typ. turn-off energy & switching times versus gate resistor, inductive switching (phaseleg)

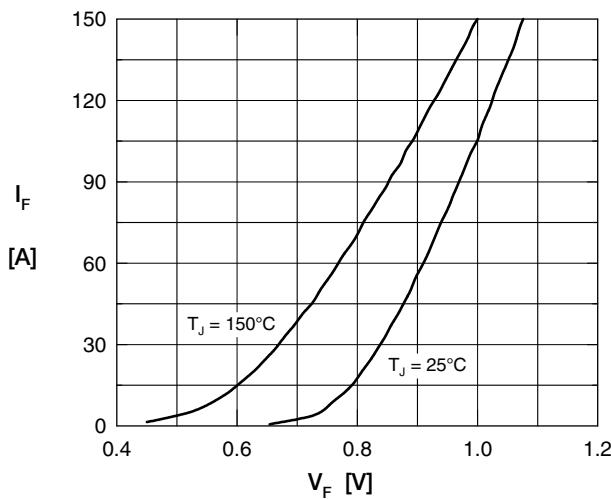


Fig. 17 Typ. forward characteristics of source drain diode D_{SD}

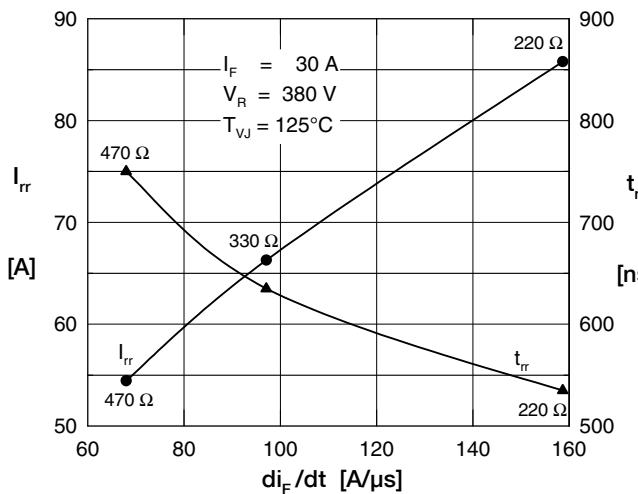


Fig. 18 Typ. reverse recovery of anti-parallel diode

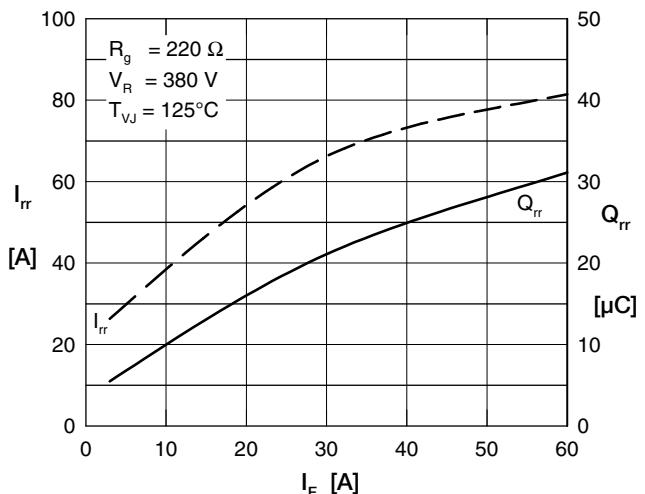


Fig. 19 Typ. reverse recovery characteristics

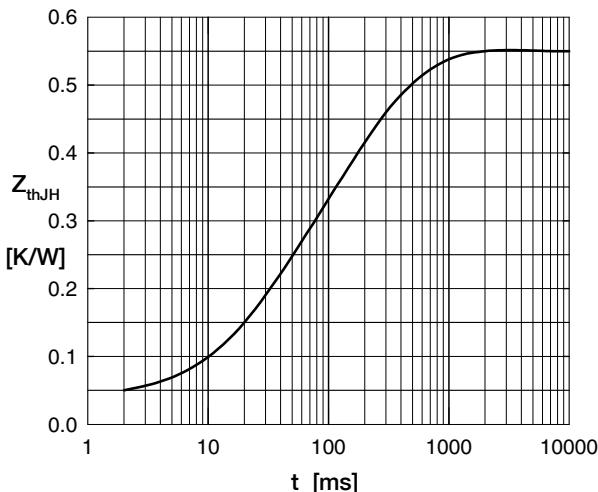


Fig. 20 Typ. transient thermal impedance of the MOSFET
(IXYS test setup)

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[DMN1006UCA6-7](#) [DMN16M9UCA6-7](#)